

RoHS

COMPLIANT

9435GP-VB Datasheet

P-Channel 30-V (D-S) MOSFET

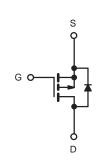
PRODUCT SUMMARY		
V _{DS}	-30	V
$R_{DS(on)}$ $V_{GS} = 10$ V	8	mΩ
$R_{DS(on)}$ $V_{GS} = 4.5$ V	11	mΩ
I _D	-70	А
Configuration	Sin	gle

FEATURES

- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch



P-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	- 30	V
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		- 70	
Continuous Drain Current ($T_{J} = 150 \text{ °C}$)	T _C = 70 °C		- 55	
$Continuous Drain Current (T_j = 150 C)$	T _A = 25 °C	- I _D	- 55	
	T _A = 70 °C		-45	٨
Pulsed Drain Current	·	I _{DM}	- 200	— A
Continuous Source-Drain Diode Current	T _C = 25 °C	1	- 50	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 50	
Avalanche Current		I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		50	
Maximum Davian Disaination	T _C = 70 °C		32	w
Maximum Power Dissipation	T _A = 25 °C	P _D	7 ^{a, b}	VV
	T _A = 70 °C	1	5 ^{a, b}	
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	0/00

Notes:

b. t = 10 s.

c. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$

d. Based on T_C = 25 °C.

TO-220AB

GDS

Top View

a. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	Cymbol			iyp.	Max.	0111	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	VGS = 0 V, ID = 200 µ/V	- 30	- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μΑ		5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1.0	0.0	- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 25 \text{ V}$	1.0		± 100	nA	
	1655	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			A	
	_	V _{GS} = - 10 V, I _D = - 10 A		8			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -8 \text{ A}$		11		mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S	
Dynamic ^b				<u> </u>			
Input Capacitance	C _{iss}			3950			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		455		pF	
Reverse Transfer Capacitance	C _{rss}			390			
Tatal Oata Ohanna		V_{DS} = - 15 V, V_{GS} = - 10 V, I_{D} = - 10 A		57	86		
Total Gate Charge	Qg			29.5	45		
Gate-Source Charge	Q_gs	V_{DS} = - 15 V, V_{GS} = - 4.5 V, I_{D} = - 10 A		8		nC	
Gate-Drain Charge	Q _{gd}			22			
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70		
Fall Time	t _f	_		9	18		
Turn-On Delay Time	t _{d(on)}			48	80	ns	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_D\cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		34	60		
Fall Time	t _f			19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	۱ _s	T _C = 25 °C			- 4.1		
Pulse Diode Forward Current	I _{SM}				- 60	A	
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			16	27	nC	
Reverse Recovery Fall Time	ta	I _F = - 10 A, dl/dt = 100 A/μs, T _J = 25 °C		12			
Reverse Recovery Rise Time	t _b			15		ns	

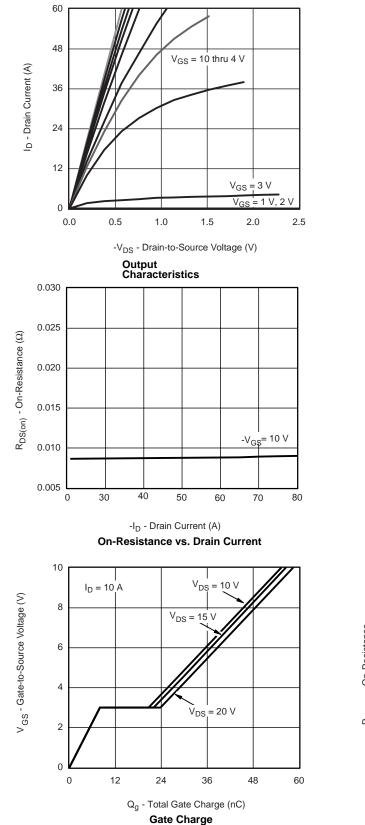
Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

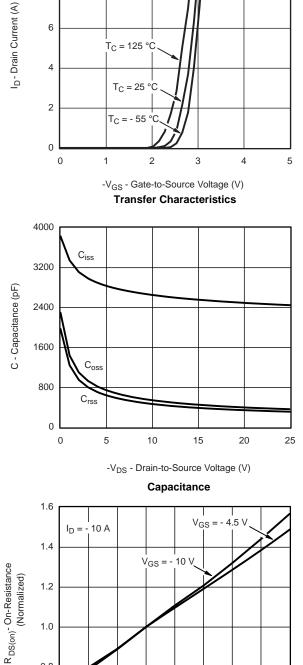
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



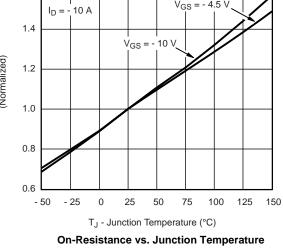


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



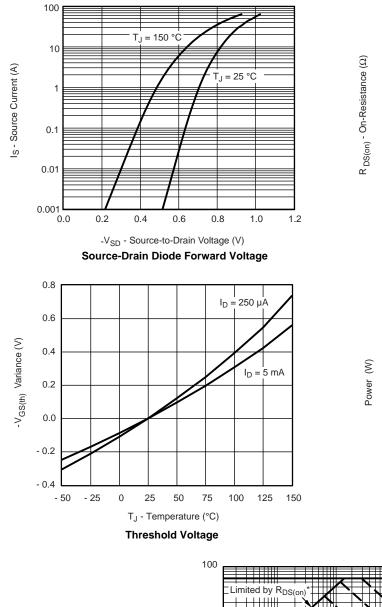
10

8

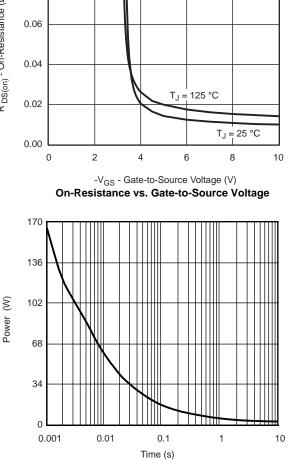




I_D = 10 A



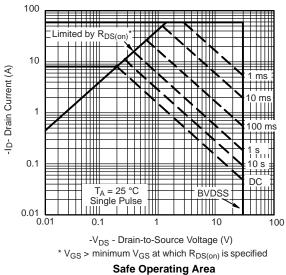
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



0.10

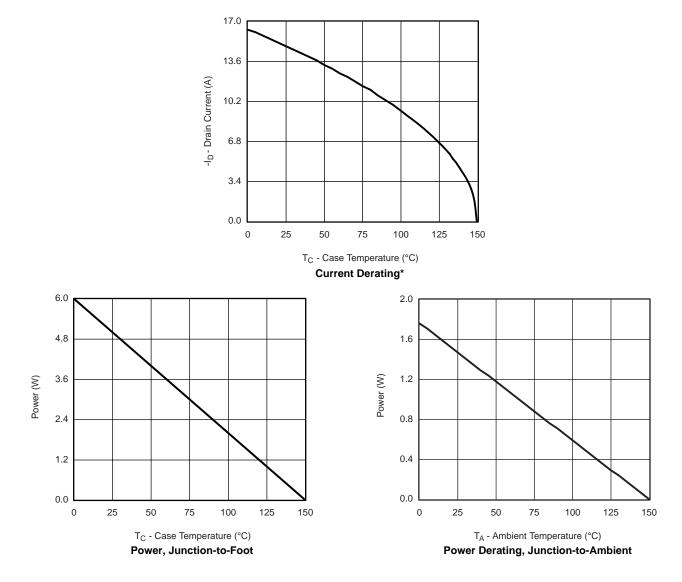
0.08

Single Pulse Power, Junction-to-Ambient





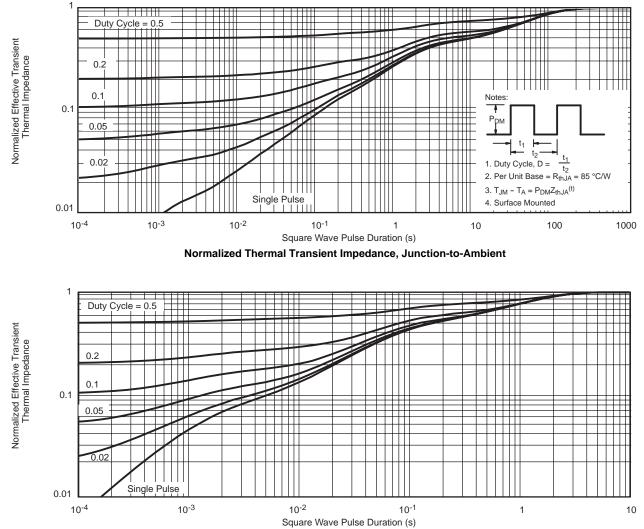
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



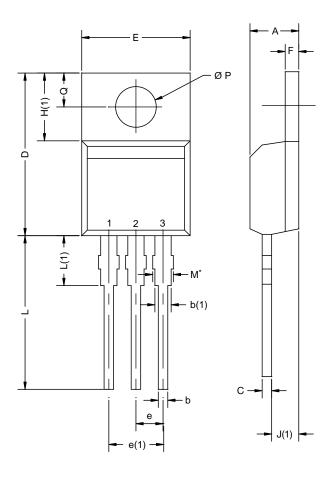
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-220AB



	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12- DWG: 547	-0208-Rev. N, 1	08-Oct-12			

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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